

0.2 W L, S-BAND POWER GaAs MES FET

DESCRIPTION

The NE650R279A is a 0.2 W GaAs MES FET designed for middle power transmitter applications for mobile communication handset and base station systems. It is capable of delivering 0.2 watt of output power (CW) with high linear gain, high efficiency, excellent distortion and is suitable as a driver amplifier for our NE6500379A etc.

Reliability and performance uniformity are assured by NEC's stringent quality and control procedures.

FEATURES

- High Output Power : $P_{O(1\text{ dB})} = +23\text{ dBm typ.}$
- High Linear Gain : 16 dB typ.
- High Power Added Efficiency: $45\% \text{ typ. @ } V_{DS} = 6\text{ V, } I_{Dset} = 50\text{ mA, } f = 1.9\text{ GHz}$

ORDERING INFORMATION (PLAN)

Part Number	Package	Supplying Form
NE650R279A-T1	79A	12 mm tape width, 1 kpcs/reel

Remark To order evaluation samples, please contact your local NEC sales office.
(Part number for sample order: NE650R279A)

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$)

Operation in excess of any one of these parameters may result in permanent damage.

Parameter	Symbol	Ratings	Unit
Drain to Source Voltage	V_{DS}	15	V
Gate to Source Voltage	V_{GSO}	-7	V
Drain Current	I_D	0.3	A
Gate Forward Current	I_{GF}	8	mA
Gate Reverse Current	I_{GR}	8	mA
Total Power Dissipation	P_T	2.1	W
Channel Temperature	T_{ch}	150	$^\circ\text{C}$
Storage Temperature	T_{stg}	-65 to +150	$^\circ\text{C}$

Caution Please handle this device at static-free workstation, because this is an electrostatic sensitive device.

The information in this document is subject to change without notice.

RECOMMENDED OPERATING LIMITS

Characteristics	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Drain to Source Voltage	V_{DS}			6.0	6.0	V
Gain Compression	Gcomp				3.0	dB
Channel Temperature	T_{ch}				+125	°C

ELECTRICAL CHARACTERISTICS

($T_A = 25^\circ\text{C}$, Unless otherwise specified, using NEC standard test fixture.)

Characteristics	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Saturated Drain Current	I_{DSS}	$V_{DS} = 2.5\text{ V}$, $V_{GS} = 0\text{ V}$		150		mA
Pinch-off Voltage	V_P	$V_{DS} = 2.5\text{ V}$, $I_D = 1\text{ mA}$	-2.5		-0.5	V
Gate to Drain Break Down Voltage	BV_{gd}	$I_{gd} = 1\text{ mA}$	13			V
Thermal Resistance	R_{th}	Channel to Case		40	60	°C/W
Output Power at 1 dB Gain Compression Point	P_O (1 dB)	$f = 1.9\text{ GHz}$, $V_{DS} = 6.0\text{ V}$ $R_g = 30\ \Omega$ $I_{Dset} = 50\text{ mA}$ (RF OFF) Note 2		23.0		dBm
Drain Current	I_D			72		mA
Power Added Efficiency	η_{add}			45		%
Linear Gain ^{Note 1}	G_L		15.0	16.0		dB

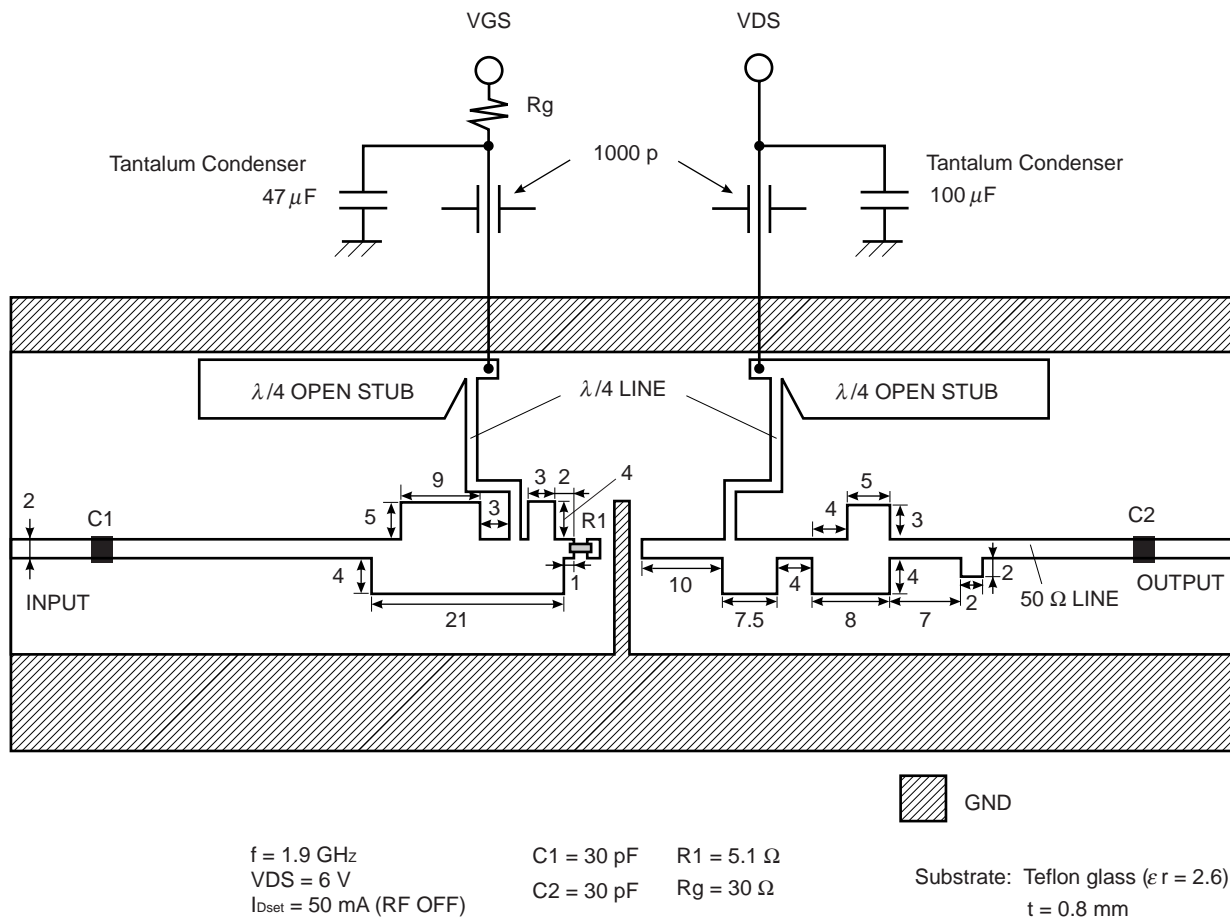
Notes 1. Pin = 0 dBm

2. DC performance is 100% testing. RF performance is testing several samples per wafer.
 Wafer rejection criteria for standard devices is 1 reject for several samples.

NE650R279A S-PARAMETERS TEST CONDITIONS: $V_{DS} = 6.0\text{ V}$, $I_{Dset} = 50\text{ mA}$ (Preliminary Data)

freq. (MHz)	S ₁₁		S ₂₁		S ₁₂		S ₂₂	
	MAG.	ANG. (deg.)	MAG.	ANG. (deg.)	MAG.	ANG. (deg.)	MAG.	ANG. (deg.)
1400	0.865	-103.4	5.788	133.2	0.070	53.2	0.403	-73.5
1500	0.861	-108.0	5.593	131.9	0.072	51.5	0.397	-76.7
1600	0.850	-112.1	5.439	130.8	0.073	51.1	0.392	-79.2
1700	0.839	-116.0	5.182	129.1	0.075	50.9	0.387	-82.1
1800	0.833	-120.5	5.026	129.1	0.078	50.6	0.382	-84.9
1900	0.827	-124.9	4.992	128.4	0.081	49.2	0.376	-87.5
2000	0.817	-129.4	4.888	125.6	0.082	47.2	0.368	-90.2
2100	0.809	-133.1	4.739	124.9	0.082	45.8	0.360	-93.0
2200	0.806	-137.7	4.628	123.6	0.081	45.6	0.349	-95.7
2300	0.795	-143.0	4.518	121.8	0.081	46.2	0.336	-98.5
2400	0.789	-148.3	4.403	119.9	0.083	46.5	0.325	-101.6
2500	0.781	-153.4	4.383	118.2	0.086	46.0	0.311	-104.9
2600	0.778	-157.5	4.348	116.6	0.087	44.3	0.300	-107.6
2700	0.779	-162.9	4.065	115.8	0.087	42.7	0.288	-110.5
2800	0.778	-167.0	3.910	113.8	0.085	42.2	0.276	-113.5
2900	0.778	-172.1	3.763	113.1	0.084	42.1	0.264	-117.3
3000	0.781	-176.7	3.632	112.8	0.083	41.4	0.256	-121.0

APPLICATION CIRCUIT EXAMPLE (Unit: mm)



[illegible]

Technical drawing of a PCB layout for a 33-hole array. The layout includes a central 33-hole array (3 rows by 11 columns) with a 1.7x4.0 inch footprint. It is flanked by a "Drain" pad (1.2x1.0 inch) on the left and a "Gate" pad (1.0x1.0 inch) on the right. The overall dimensions are 6.1 inches wide and 5.9 inches high. A note indicates to "Stop up the hole with a rosin or something to avoid solder flow." and a dimension of 0.2 x 33 is given for the through holes.

RECOMMENDED SOLDERING CONDITIONS

This product should be soldered under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your NEC sales representative.

Soldering Method	Soldering Conditions	Recommended Condition Symbol
Infrared Reflow	Package peak temperature: 235°C or below Time: 30 seconds or less (at 210°C) Count: 2, Exposure limit ^{Note} : None	IR35-00-2
Partial Heating	Pin temperature: 260°C Time: 5 seconds or less (per pin row) Exposure limit ^{Note} : None	—

Note After opening the dry pack, keep it in a place below 25°C and 65% RH for the allowable storage period.

Caution Do not use different soldering methods together (except for partial heating).

[MEMO]

Caution

The Great Care must be taken in dealing with the devices in this guide.

The reason is that the material of the devices is GaAs (Gallium Arsenide), which is designated as harmful substance according to the law concerned.

Keep the law concerned and so on, especially in case of removal.

The application circuits and their parameters are for reference only and are not intended for use in actual design-ins.

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NEC devices are classified into the following three quality grades:

"Standard", "Special", and "Specific". The Specific quality grade applies only to devices developed based on a customer designated "quality assurance program" for a specific application. The recommended applications of a device depend on its quality grade, as indicated below. Customers must check the quality grade of each device before using it in a particular application.

Standard: Computers, office equipment, communications equipment, test and measurement equipment, audio and visual equipment, home electronic appliances, machine tools, personal electronic equipment and industrial robots

Special: Transportation equipment (automobiles, trains, ships, etc.), traffic control systems, anti-disaster systems, anti-crime systems, safety equipment and medical equipment (not specifically designed for life support)

Specific: Aircrafts, aerospace equipment, submersible repeaters, nuclear reactor control systems, life support systems or medical equipment for life support, etc.

The quality grade of NEC devices is "Standard" unless otherwise specified in NEC's Data Sheets or Data Books. If customers intend to use NEC devices for applications other than those specified for Standard quality grade, they should contact an NEC sales representative in advance.

Anti-radioactive design is not implemented in this product.